Zener Diode

Unit: mm

DZ26360×0L

Panasonic

DZ26360×0L

Silicon epitaxial planar type

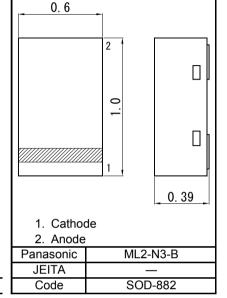
For constant voltage / For surge absorption circuit DZ27360 in ML2 type package

■ Features

- Excellent rising characteristics of zener current IZ
- · Low zener operating resistance RZ
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol : JG or JR

■ Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)



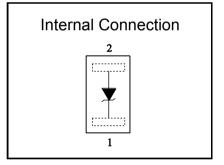
■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	100	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 PT = 100 mW achieved with a printed circuit board.

*2 Test method:IEC61000_4_2

(C = 150 pF , R = 330 Ω , Contact discharge : 10 times)



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 2 mA	34.20		37.80	V
Zener operating resistance	RZ	IZ = 2 mA			250	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			250	Ω
Reverse current	IR	VR = 27 V			0.05	μА
Temperature coefficient of zener voltage *3	SZ	IZ = 2 mA		35.4		mV/°C

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 - 2. Absolute frequency of input and output is 5 MHz.
 - 3. *1 The temperature must be controlled 25 °C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25 °C)
 - *2 VZ guaranteed 20 ms after current flow.
 - *3 Tj = 25 °C to 150 °C

Rank classification

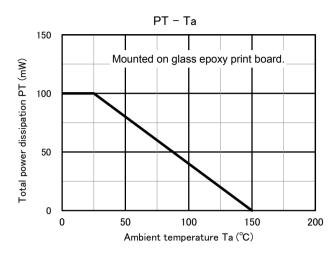
Code	M			0		
Rank	M		No-rank			
VZ	35.10	to	36.90	34.20	to	37.80
Marking symbol		JR			JG	

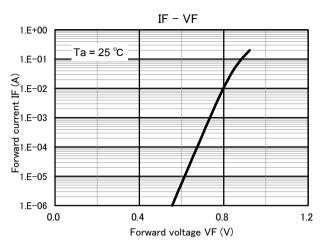
Established : 2013-04-20 Revised : 2017-01-10 **Panasonic**

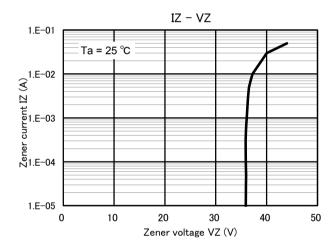
Zener Diode

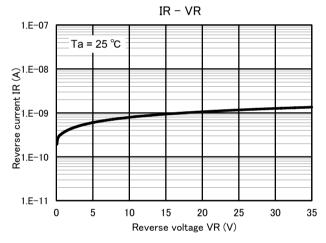
DZ26360×0L

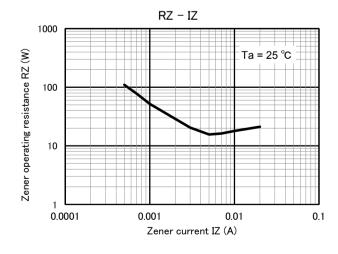
Technical Data (reference)

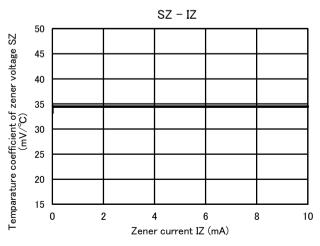










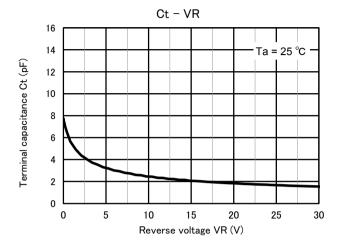


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Established: 2013-04-20 Revised: 2017-01-10 Zener Diode

DZ26360×0L

Technical Data (reference)

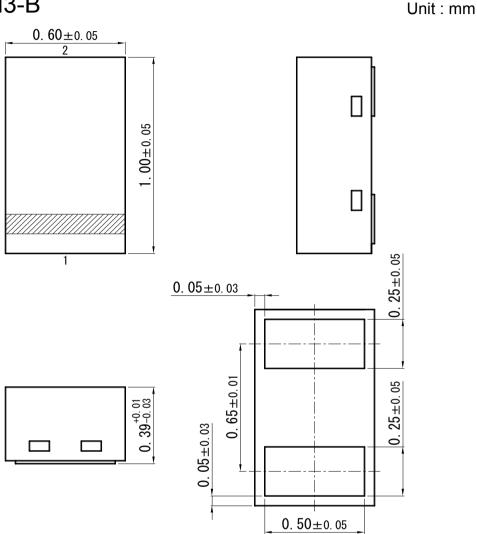


Zener Diode

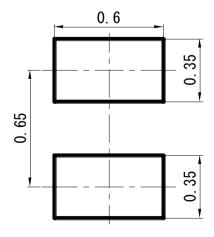
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ML2-N3-B



■ Land Pattern (Reference) (Unit: mm)



Page 4 of 4

Established: 2013-04-20 Revised: 2017-01-10

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